



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-12-22
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T3035H-6G	7BD1*306SBT1	A	SHENZHEN B/E	2016-12-22
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	GULL WING	

Comment	Package: D2PAK CLIP; MDF valid for T3035H-6G-TR
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QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	78D1*3065BT1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	16.780	mg	supplier	die	Silicon (Si)	7440-21-3		14.545	mg	866806	10540
				supplier	metallization	Nickel (Ni)	7440-02-0		0.292	mg	17402	212
				supplier	metallization	Gold (Au)	7440-57-5		0.055	mg	3278	40
				supplier	Passivation	Silicon Oxide	7631-86-9		0.083	mg	4946	60
				supplier	back side metallization	Gold (Au)	7440-57-5		0.019	mg	1132	14
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.395	mg	23540	286
				supplier	glass coating	Glass : Aluminium Oxide	1344-28-1		0.117	mg	6973	85
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	1.274	mg	75924	923
Leadframe	Copper & its alloys	900.740	mg	supplier	alloy	Copper (Cu)	7440-50-8		899.839	mg	999000	652057
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.901	mg	1000	653
Soft solder	Solder	15.294	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	14.147	mg	925003	10251
				supplier	solder	Silver (Ag)	7440-22-4		0.765	mg	50020	554
				supplier	solder	Tin (Sn)	7440-31-5		0.382	mg	24977	277
				supplier	solder	Silver (Ag)	7440-22-4		0.765	mg	50020	554
Encapsulation	Other Organic Materials	409.247	mg	supplier	mold compound	Silica, vitreous	60676-86-0		311.028	mg	760001	225383
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		41.743	mg	102000	30249
				supplier	mold compound	Phenol resin	9003-35-4		24.555	mg	60000	17793
				supplier	mold compound	Others	Proprietary		20.462	mg	49999	14828
				supplier	mold compound	Metal hydroxide	Proprietary		8.185	mg	20000	5931
				supplier	mold compound	Carbon black	1333-86-4		3.274	mg	8000	2372
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575
Clip		31.625	mg	supplier	alloy	Copper ( Cu)	7440-50-8		31.625	mg	1000000	22917